

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM}	100	V
Average Rectified Output Current	I _O	8	A
Non-Repetitive Peak Forward Surge Current 8.3mS	I _{FSM}	130	A
Non-Repetitive Avalanche Energy at I _{AS} = 5.0A, L = 50mH	E _{AS}	400	mJ
Non-Repetitive Avalanche Energy at I _{AS} = 20.0A, L = 1mH	E _{AS}	150	mJ
Electrostatic Discharge	HBM	4000	V
Electrostatic Discharge	MM	400	V
Electrostatic Discharge	CDM	1	kV

Thermal Characteristics (Note 9)

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	25	°C/W
Typical Thermal Resistance Junction to Ambient (Note 7)	R _{θJA}	90	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	0.72	—	V	I _F = 4A, T _J = +25°C
		—	0.78	0.88		I _F = 8A, T _J = +25°C
		—	0.59	—		I _F = 4A, T _J = +125°C
		—	0.65	0.74		I _F = 8A, T _J = +125°C
Leakage Current (Note 8)	I _R	—	0.08	2.0	μA	V _R = 100V, T _J = +25°C
		—	15	100		V _R = 100V, T _J = +125°C
Junction Capacitance	C _J	—	245	—	pF	V _R = 4V, T _J = +25°C
Switching Speed t _{RR}	t _{RR}	—	16	—	ns	I _F = 0.5A, I _R = 1A, I _{RR} = 0.25A (RG1)

- Notes:
- 6. 2inch sq. Al board.
 - 7. MRP FR-4 PC board, 2oz.
 - 8. Short duration pulse test used to minimize self-heating effect.
 - 9. The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

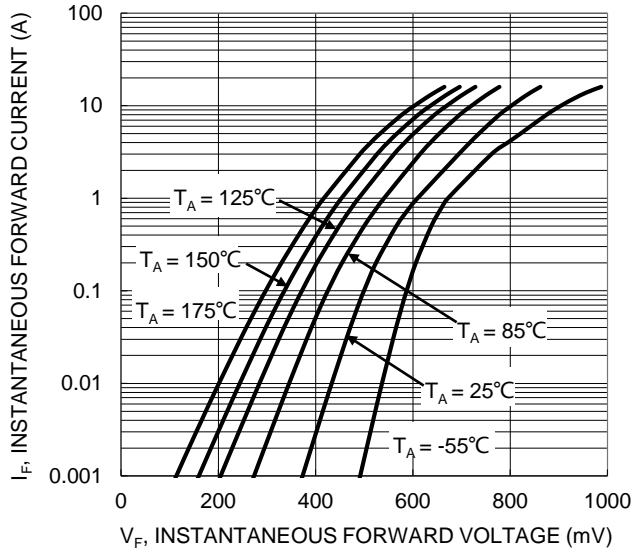


Figure 1. Typical Forward Characteristics

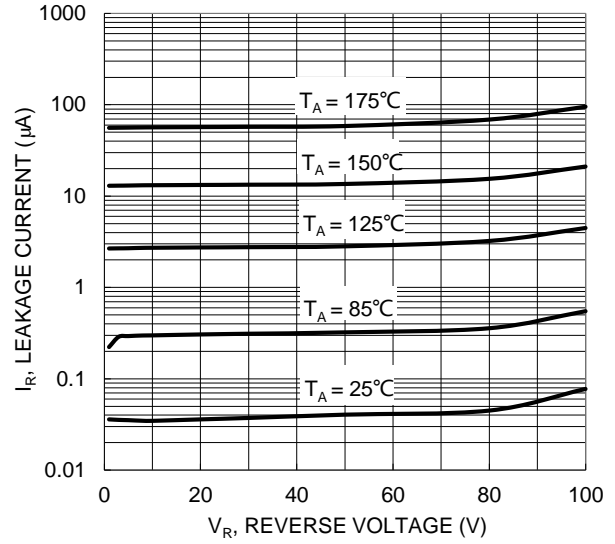


Figure 2. Typical Reverse Characteristics

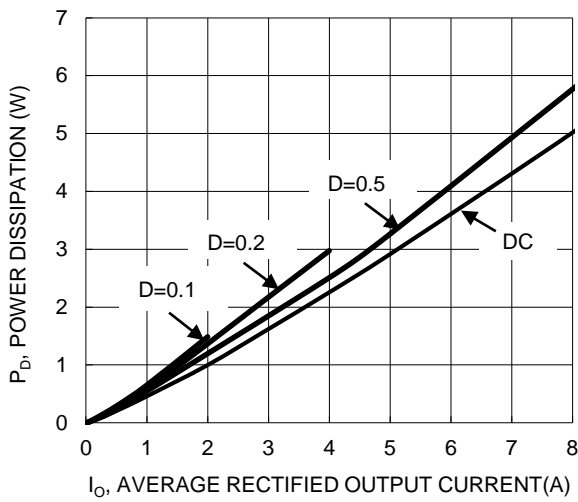


Figure 3. Forward Power Dissipation $T_J=125^\circ\text{C}$

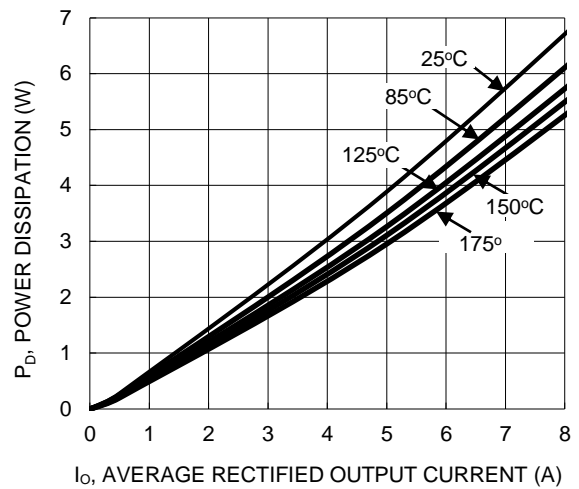


Figure 4. Forward Power Dissipation $D=0.5$

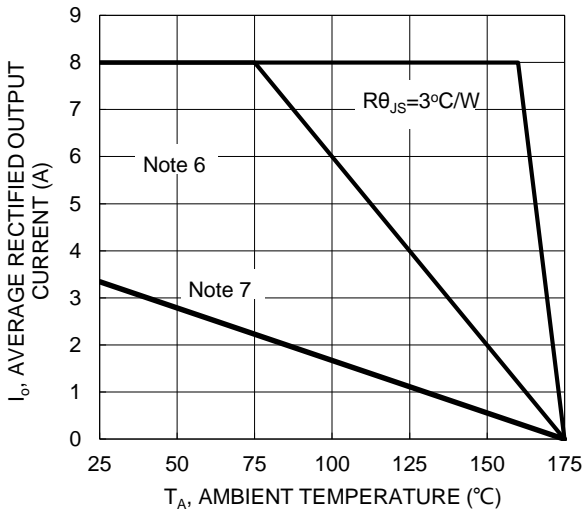


Figure 5. Forward Current Derating Curve

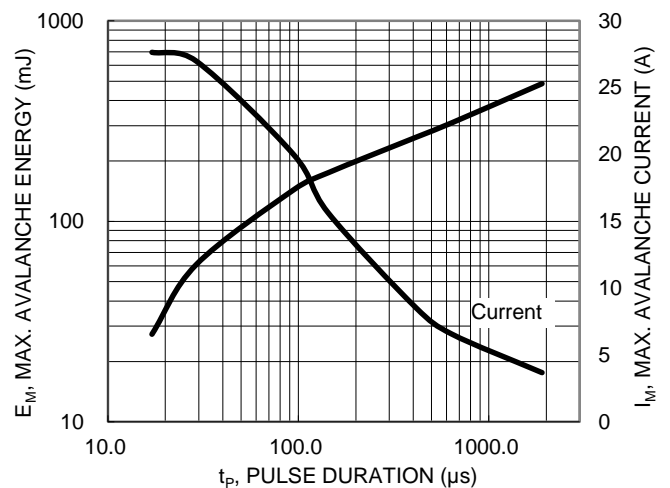


Figure 6. Typical Single Pulse Max. Avalanche Energy and Current

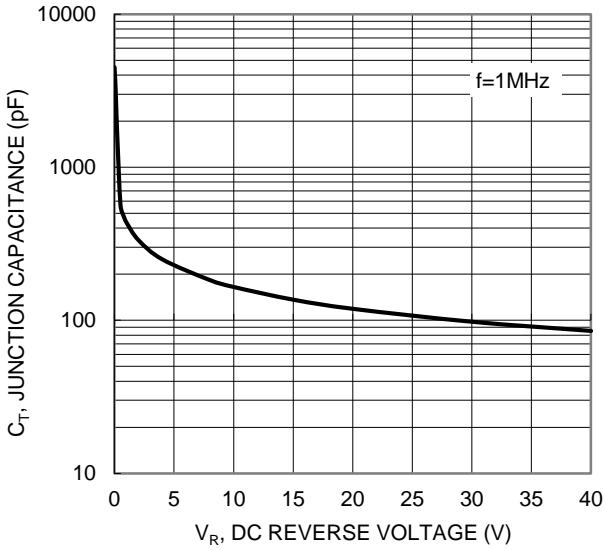


Figure 7. Typical Junction Capacitance

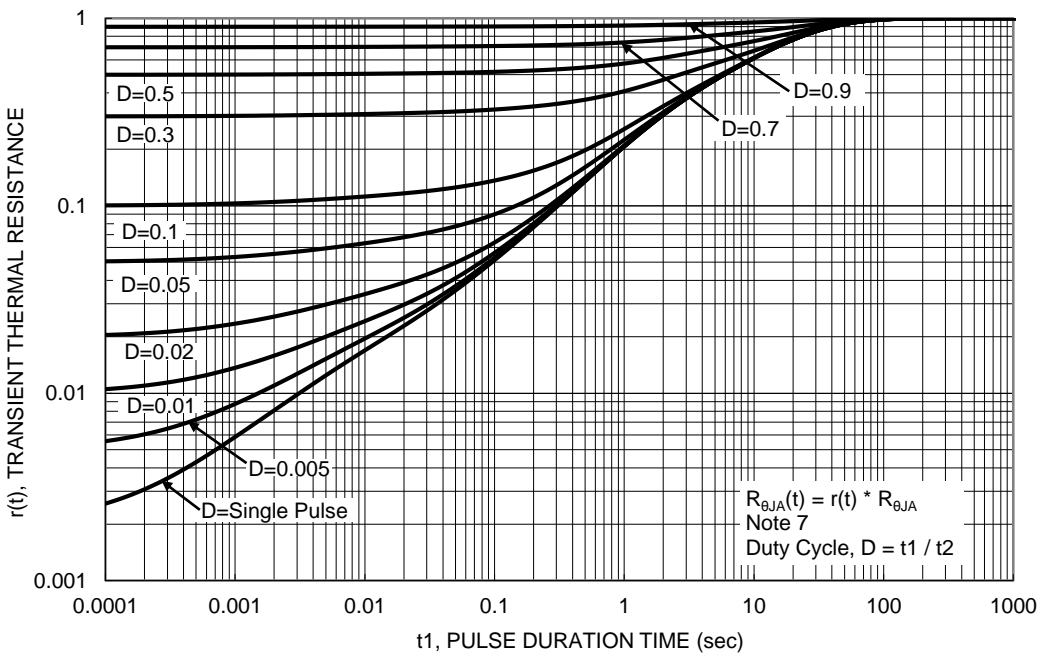
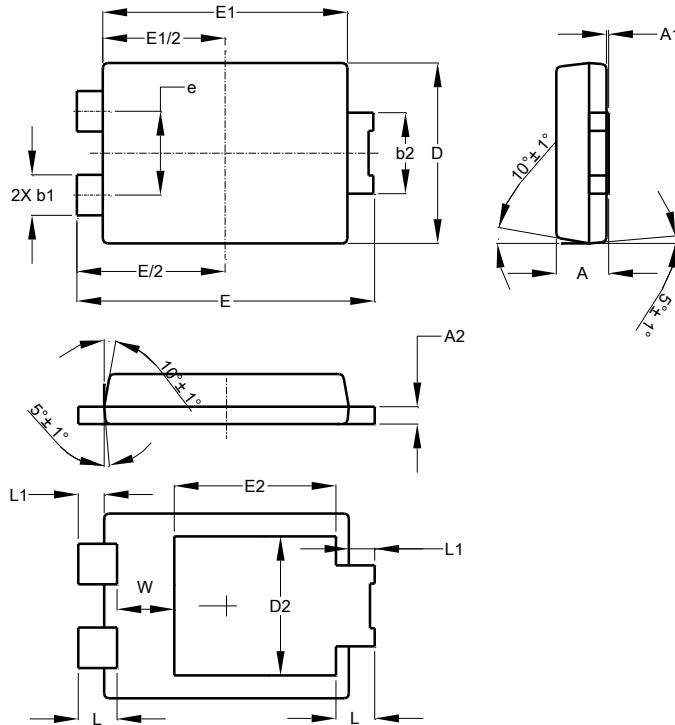


Figure 8. Transient Thermal Resistance MRP (Note 7)

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI5

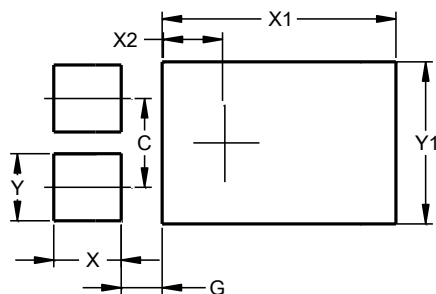


PowerDI5			
Dim	Min	Max	Typ
A	1.05	1.15	1.10
A1	0.00	0.05	--
A2	0.33	0.43	0.381
b1	0.80	0.99	0.89
b2	1.70	1.88	1.78
D	3.90	4.05	3.966
D2	--	--	3.054
E	6.40	6.60	6.51
e	--	--	1.84
E1	5.30	5.45	5.37
E2	--	--	3.549
L	0.75	0.95	0.85
L1	0.50	0.65	0.57
W	1.10	1.41	1.255
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI5



Dimensions	Value (in mm)
C	1.840
G	0.852
X	1.400
X1	4.860
X2	1.310
Y	1.390
Y1	3.360

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